# 2SD2225

### Silicon NPN epitaxial planar type

#### For low-frequency amplification

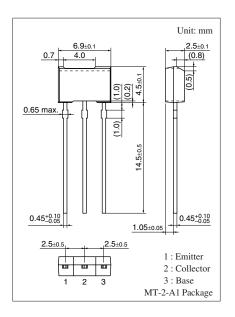
#### ■ Features

- $\bullet$  High collector-emitter voltage (Base open)  $V_{\text{CEO}}\,\text{of}\,120\,\text{V}$
- Optimum for low-frequency driver amplification
- Allowing supply with the radial taping

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	120	V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	120	V
Emitter-base voltage (Collector open)	$V_{EBO}$	5	V
Collector current	$I_{C}$	0.5	A
Peak collector current	$I_{CP}$	1	A
Collector power dissipation *	P <sub>C</sub>	1	W
Junction temperature	$T_j$	150	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

Note) \*: Printed circuit board: Copper foil area of 1 cm $^2$  or more, and the board thickness of 1.7 mm for the collector portion



#### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

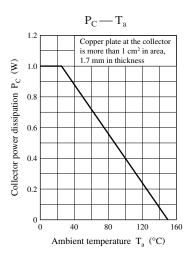
Parameter	Symbol	Conditions		Тур	Max	Unit
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 0.1 \text{ mA}, I_B = 0$	120			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_C = 10 \mu\text{A},  I_C = 0$	5			V
Forward current transfer ratio *1	h <sub>FE1</sub> *2	$V_{CE} = 10 \text{ V}, I_{C} = 150 \text{ mA}$			330	_
	h <sub>FE2</sub>	$V_{CE} = 5 \text{ V}, I_{C} = 500 \text{ mA}$	50			
	h <sub>FE3</sub>	$V_{CE} = 5 \text{ V}, I_{C} = 100 \text{ mA}$	100			
Collector-emitter saturation voltage *1	V <sub>CE(sat)</sub>	$I_C = 300 \text{ mA}, I_B = 30 \text{ mA}$		0.15	1.00	V
Base-emitter saturation voltage *1	V <sub>BE(sat)</sub>	$I_C = 300 \text{ mA}, I_B = 30 \text{ mA}$		0.9	1.2	V
Transition frequency *1	$f_T$	$V_{CB} = 10 \text{ V}, I_{E} = -50 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$		11.5	20.0	pF
(Common base, input open circuited)						

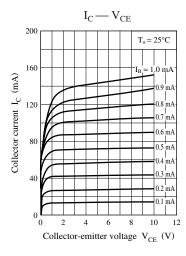
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

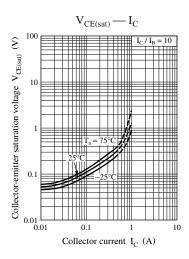
- 2. \*1: Pulse measurement
  - \*2: Rank classification

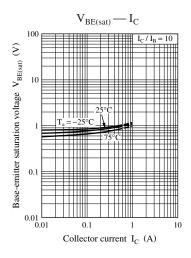
Rank	Q	R	S	
$h_{\rm FE1}$	90 to 155	130 to 220	185 to 330	

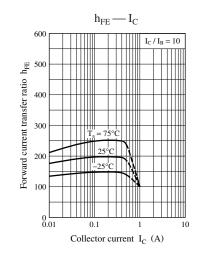
### **Panasonic**

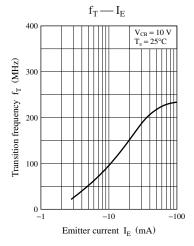


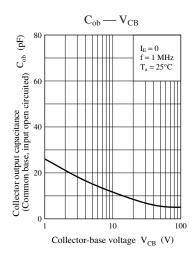












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